



HE9015

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HE9015 is designed for use in pre-amplifier of low level and low noise.

Features

- High Total Power Dissipation (PD: 450mW)
- Complementary to HE9014
- High hFE and Good Linearity

Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 450 mW
- Maximum Voltages and Currents (Ta=25°C)
 VCB0 Collector to Base Voltage -50 V
 VCEO Collector to Emitter Voltage -45 V
 VEBO Emitter to Base Voltage -5 V
 IC Collector Current -100 mA

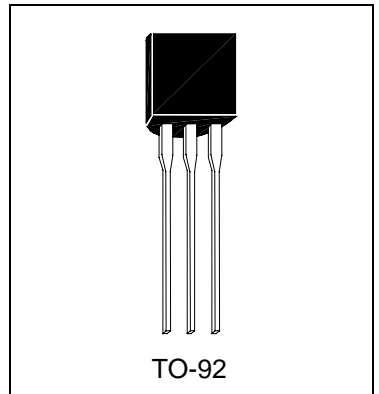
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-50	-	-	V	IC=-100uA, IE=0
BVCEO	-45	-	-	V	IC=-1mA, IB=0
BVEBO	-5	-	-	V	IE=-100uA, IC=0
ICBO	-	-	-50	nA	VCB=-50V, IE=0
IEBO	-	-	-50	nA	VEB=-5V, IC=0
*VCE(sat)	-	-0.20	-0.7	V	IC=-100mA, IB=-5mA
*VBE(sat)	-	-0.82	-1	V	IC=-100mA, IB=-5mA
VBE(on)	-0.6	-0.65	-0.75	V	VCE=-5V, IC=-2mA
*hFE	100	200	600		VCE=-5V, IC=-1mA
Cob	-	4.5	7	pF	VCB=-10V, f=1MHz, IE=0
fT	100	190	-	MHz	VCE=-5V, IC=-10mA

*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

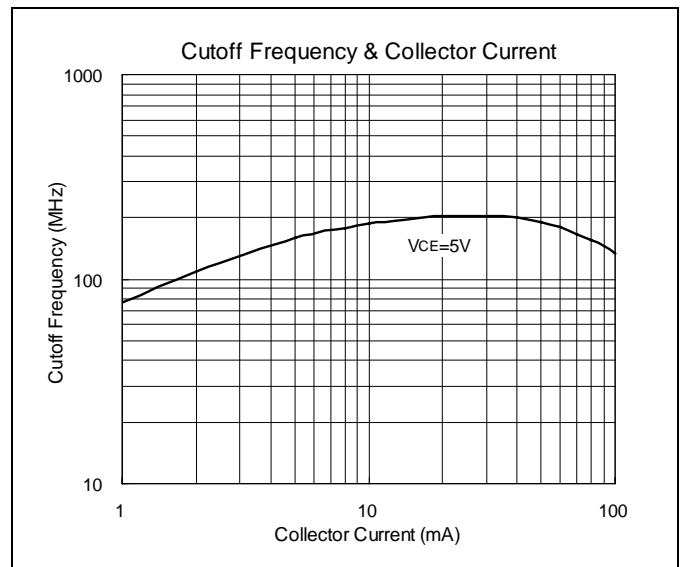
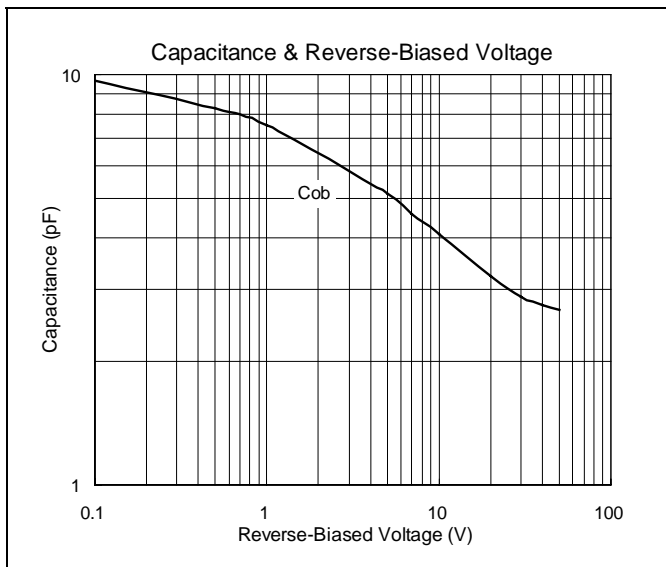
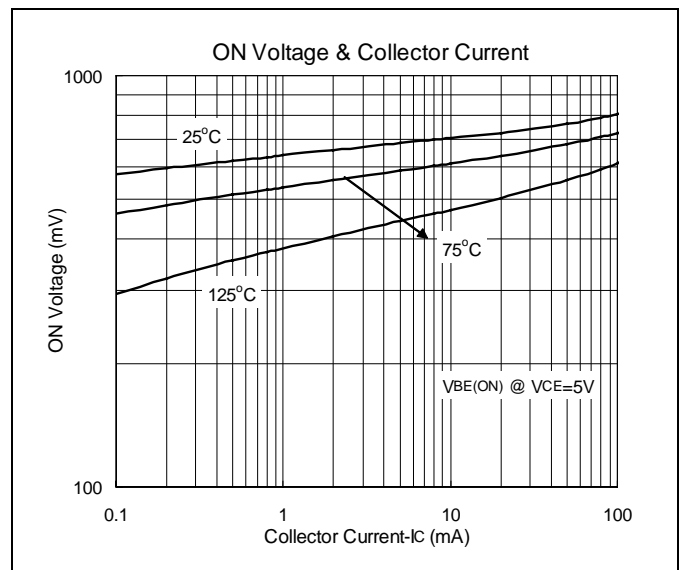
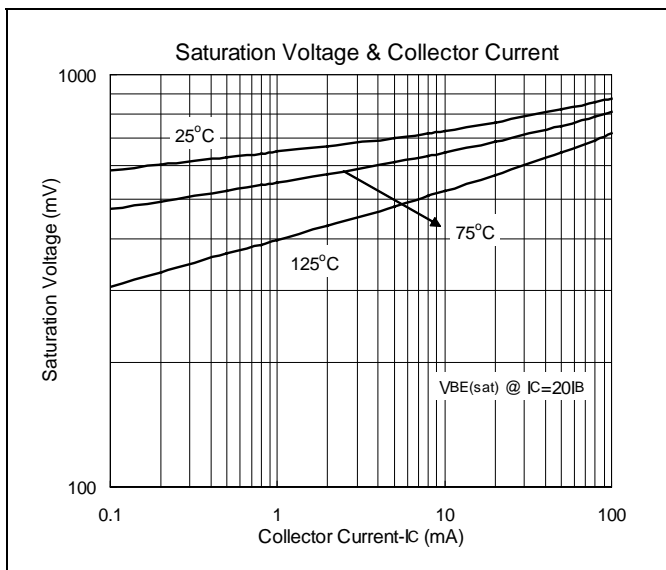
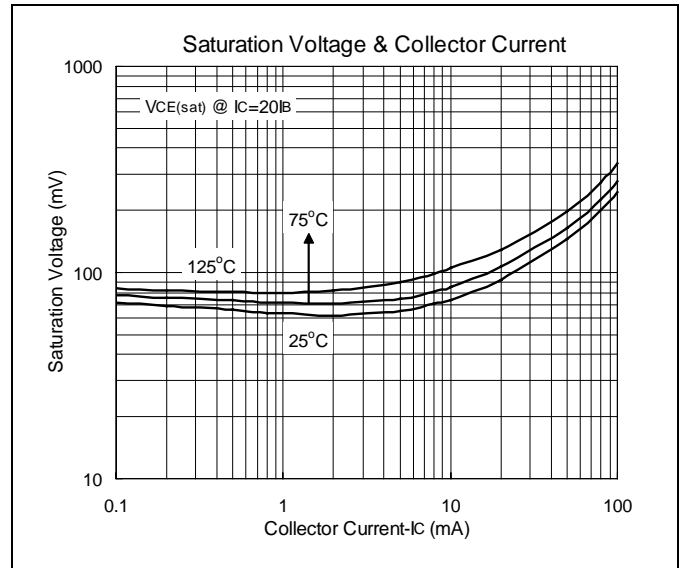
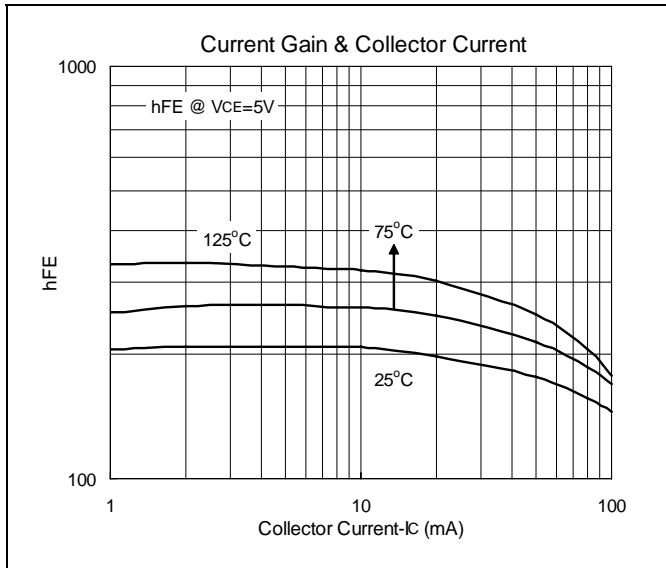
Classification on hFE1

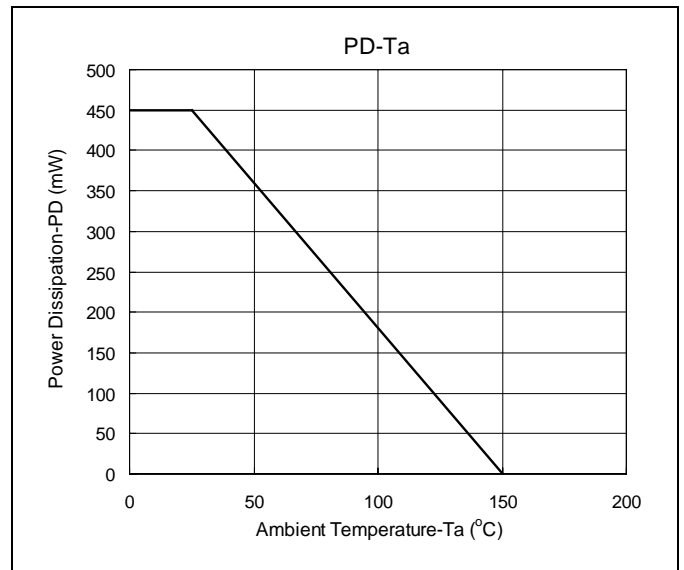
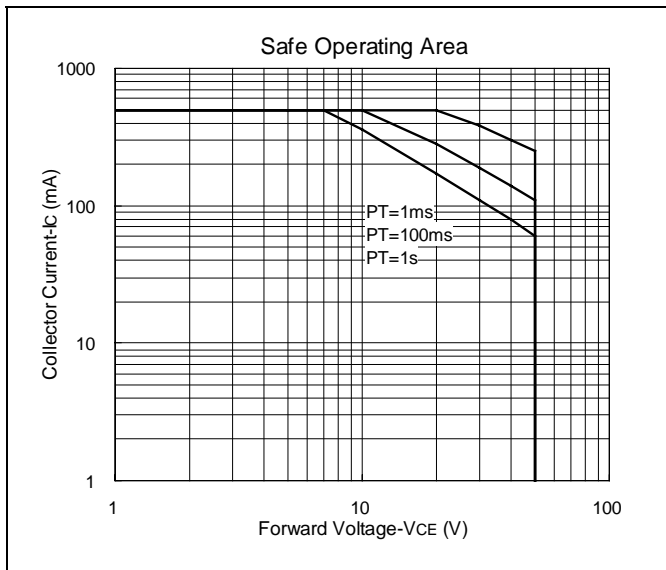
Rank	B	C
Range	100-300	200-600





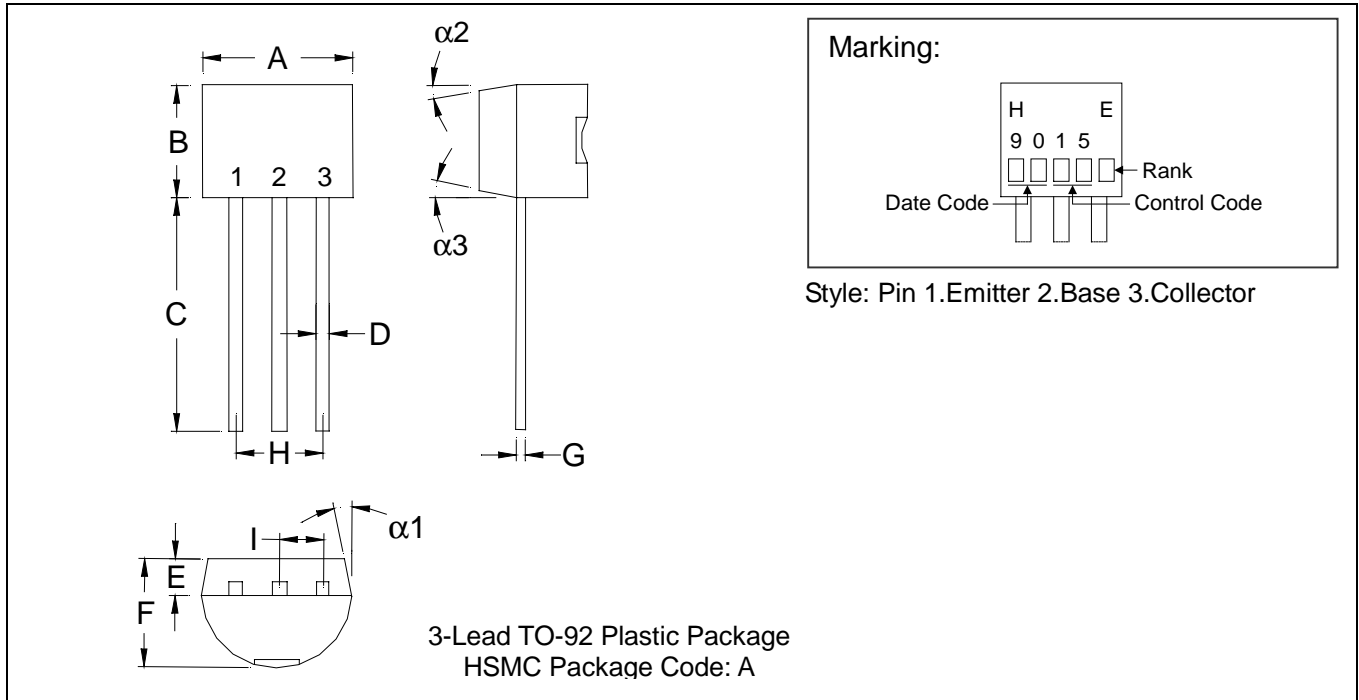
Characteristics Curve







TO-92 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

- Notes:**
1. Dimension and tolerance based on our Spec. dated Apr. 25, 1996.
 2. Controlling dimension: millimeters.
 3. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4. If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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